

## **FEATURES**

- Glass passivated device
- ◆ Ideal for surface mouted applications
- Low reverse leakage
- Metallurgically bonded construction
- High temperature soldering guaranteed: 250°C/10 seconds,0.375"(9.5mm) lead length, 5 lbs. (2.3kg) tension

## **MECHANICAL DATA**

Case: JEDEC SOD-123FL molded plastic body over passivated chip

Terminals: Solderable per MIL-STD-750,

Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 0.0007 ounce, 0.02 grams

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Catalog Number	SYMBOLS	SM4007PL	UNITS
Maximum repetitive peak reverse voltage	Vrrm	1000	VOLTS
Maximum RMS voltage	VRMS	700	VOLTS
Maximum DC blocking voltage	VDC	1000	VOLTS
Maximum average forward rectified current at Ta=65°C (NOTE 1)	l(AV)	0.9	Amp
Peak forward surge current		25.0	
8.3ms single half sine-wave superimposed on rated load (JEDEC Method) TL=25°C	IFSM	25.0	Amps
Maximum instantaneous forward voltage at 1.0A	VF	1.1	Volts
Maximum DC reverse current Ta=25°C at rated DC blocking voltage Ta=125°C	lr	10.0 50.0	μА
Typical junction capacitance (NOTE 2)	Cı	4	pF
Typical thermal resistance (NOTE 3)	Reja	180	K/W
Operating junction and storage temperature range	ТЈ,Тѕтс	-55 to +150	°C

Note: 1. Averaged over any 20ms period.

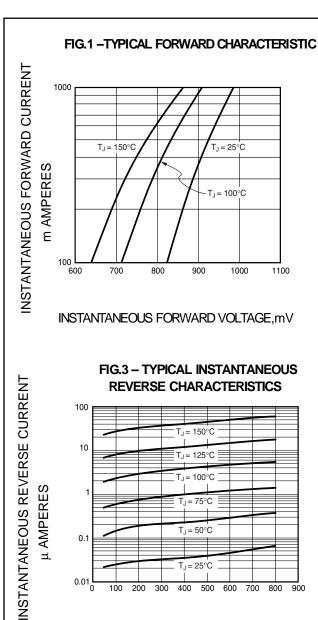
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3. Thermal resistance from junction to ambient at 0.375" (9.5mm)lead length, P.C.B. mounted





μ AMPERES



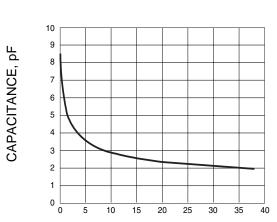
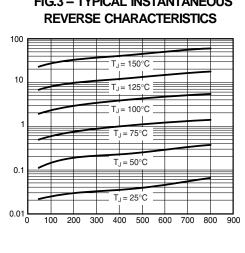
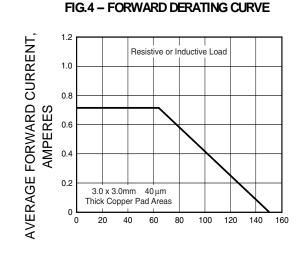


FIG.2 - TYPICAL JUNCTION CAPACITANCE

REVERSE VOLTAGE, VOLTS



INSTANTANEOUS REVERSE VOLTAGE, V



AMBIENT TEMPERATURED